

IN THE CLAIMS:

1. (Currently Amended) A semiconductor integrated circuit comprising:  
pads on a surface of a semiconductor substrate, and  
a plurality of wirings electrically connected to the pads,  
wherein said wirings are located for contacting bumps on a probe card, when such a card is  
located parallel to said surface of the semiconductor substrate and contiguous to said wirings, but  
spaced from said pads.
2. (Previously Presented) A semiconductor integrated circuit as defined in Claim 1  
comprising at least two of said wirings, both of which physically contact one of said bumps,  
without touching each other.
3. (Previously Presented) A semiconductor integrated circuit as defined in Claim 2  
wherein each of said wirings has at least one bent portion or angular portion for directly contacting  
one or more bumps.
4. (Currently Amended) A semiconductor integrated circuit as defined in Claim 2 wherein said  
wirings have electrically separable portions for electrically disconnecting said wirings from said  
pads.